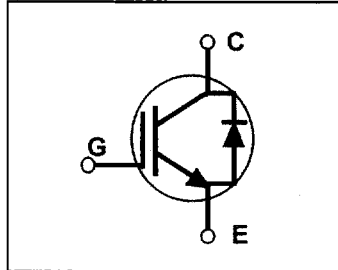
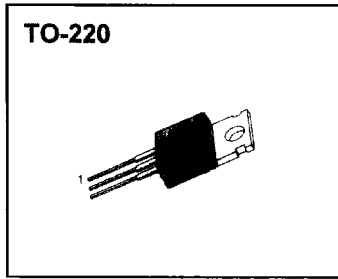


FEATURES

- * Short Circuit rated 10uS @Tc=100°C
- * High Speed Switching
- * Low Saturation Volatge
: $V_{CE(sat)} = 2.0\text{ V @ } I_c=5\text{A}$
- * High Input Impedance
- * CO-PAK, IGBT with FRD
: $T_{rr} = 37\text{nS (Typ.)}$

APPLICATIONS

- * AC & DC Motor controls
- * General Purpose Inverters
- * Robotics , Servo Controls
- * Power Supply
- * Lamp Ballast



2

ABSOLUTE MAXIMUM RATINGS

| Symbol | Characteristics | Rating | Units |
|-------------|---|-----------|-------|
| V_{CES} | Collector-Emitter Voltage | 600 | V |
| V_{GES} | Gate-Emitter Voltage | ± 20 | V |
| I_C | Collector Current @ Tc = 25°C | 8 | A |
| | Collector Current @ Tc = 100°C | 5 | A |
| $I_{CM(1)}$ | Pulsed Collector Current | 15 | A |
| I_F | Diode Continuous Forward Current @ Tc = 100°C | 8 | A |
| I_{FM} | Diode Maximum Forward Current | 56 | A |
| P_D | Maximum Power Dissipation @Tc = 25°C | 60 | W |
| | Maximum Power Dissipation @Tc = 100°C | 25 | W |
| Tsc | Short Circuit Withstand Time | 10 | uS |
| Tj | Operating Junction Temperature | -55 ~ 150 | °C |
| Tstg | Storage Temperature Range | -55 ~ 150 | °C |
| TL | Maximum Lead Temp. For Soldering | 300 | °C |
| | Purposes, 1/8" from case for 5 seconds | | |

Notes: (1) Repetitive rating : Pulse width limited by max. junction temperature

ELECTRICAL CHARACTERISTICS (IGBT PART)

(T_c=25 °C, Unless Otherwise Specified)

| Symbol | Characteristics | Test Conditions | Min | Typ | Max | Units | |
|--|--|---|---|-----|-----|-------|----|
| BV _{CES} | C - E Breakdown Voltage | V _{GE} = 0V, I _C = 250 μA | 600 | - | - | V | |
| ΔV _{CES} / ΔT _J | Temperature Coeff. of Breakdown Voltage | V _{GE} = 0V, I _C = 1mA | - | 0.6 | - | V/°C | |
| V _{GE(th)} | G - E threshold voltage | I _C = 5mA, V _{CE} = V _{GE} | 5.0 | 6.0 | 8.0 | V | |
| I _{CES} | Collector cutoff Current | V _{CE} = V _{CES} , V _{GE} = 0V | - | - | 250 | μA | |
| I _{GES} | G - E leakage Current | V _{GE} = V _{GES} , V _{CE} = 0V | - | - | 100 | nA | |
| V _{CE(sat)} | Collector to Emitter saturation voltage | I _C = 5A, V _{GE} = 15V | - | 2.0 | 2.7 | V | |
| | | I _C = 8A, V _{GE} = 15V | - | 2.5 | - | V | |
| C _{ies} | Input capacitance | V _{GE} = 0V, f = 1MHz V _{CE} = 30V | - | 337 | - | pF | |
| C _{oes} | Output capacitance | | - | 60 | - | pF | |
| C _{res} | Reverse transfer capacitance | | - | 13 | - | pF | |
| t _{d(on)} | Turn on delay time | V _{CC} = 300V, I _C = 5A V _{GE} = 15V R _G = 40 Ω Inductive Load | - | 9 | - | nS | |
| t _r | Turn on rise time | | - | 18 | - | nS | |
| t _{d(off)} | Turn off delay time | | - | 46 | 75 | nS | |
| t _f | Turn off fall time | | - | 140 | 280 | nS | |
| E _{on} | Turn on Switching Loss | | - | 80 | - | μJ | |
| E _{off} | Turn off Switching Loss | | - | 100 | - | μJ | |
| E _{ts} | Total Switching Loss | | - | 180 | 270 | μJ | |
| T _{sc} | Short Circuit withstand Time | | V _{CC} = 300V, V _{GE} = 15V @T _c = 100 °C | 10 | - | - | μS |
| Q _g | Total Gate Charge | | V _{CC} = 300V V _{GE} = 15V I _C = 5A | - | 24 | 36 | nC |
| Q _{ge} | Gate-Emitter Charge | | | - | 7 | 10 | nC |
| Q _{gc} | Gate-Collector Charge | - | | 8 | 12 | nC | |

ELECTRICAL CHARACTERISTICS (DIODE PART)

(T_c=25 °C, Unless Otherwise Specified)

| Symbol | Characteristics | Test Conditions | Min | Typ | Max | Units | |
|-----------------|-------------------------------------|--|-------------------------|-----|-----|-------|----|
| V _{FM} | Diode Forward Voltage | I _F =8.0A | T _c = 25 °C | - | 1.4 | 1.7 | V |
| | | | T _c = 100 °C | - | 1.3 | - | |
| T _{rr} | Diode Reverse Recovery Time | | T _c = 25 °C | - | 37 | 55 | nS |
| | | | T _c = 100 °C | - | 55 | - | |
| I _{rr} | Diode Peak Reverse Recovery Current | I _F =8.0A, V _R =200V -di/dt=200A/uS | T _c = 25 °C | - | 3.5 | 5.0 | A |
| | | | T _c = 100 °C | - | 4.5 | - | |
| Q _{rr} | Diode Reverse Recovery Charge | | T _c = 25 °C | - | 65 | 138 | nC |
| | | | T _c = 100 °C | - | 124 | - | |

2

THERMAL RESISTANCE

| Symbol | Characteristics | Min | Typ | Max | Units |
|------------------|--------------------------|-----|-----|-----|-------|
| R _{θJC} | Junction-to-Case (IGBT) | - | - | 2.0 | °C/W |
| R _{θJC} | Junction-to-Case (DIODE) | - | - | 3.5 | °C/W |
| R _{θJA} | Junction-to-Ambient | - | - | 80 | °C/W |
| R _{θCS} | Case-to-Sink | - | 0.5 | - | °C/W |

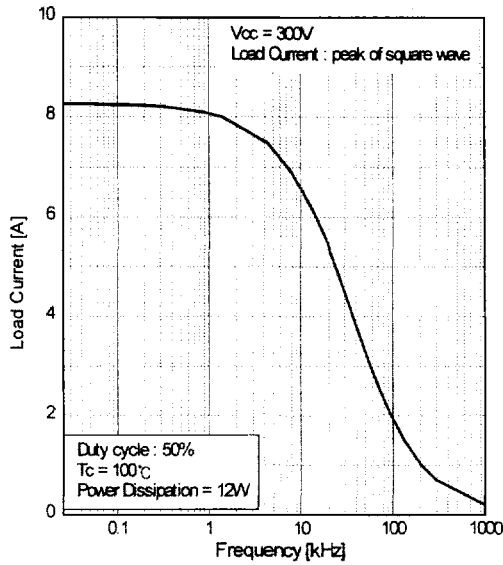


Fig.1 Typical Load Current vs. Frequency

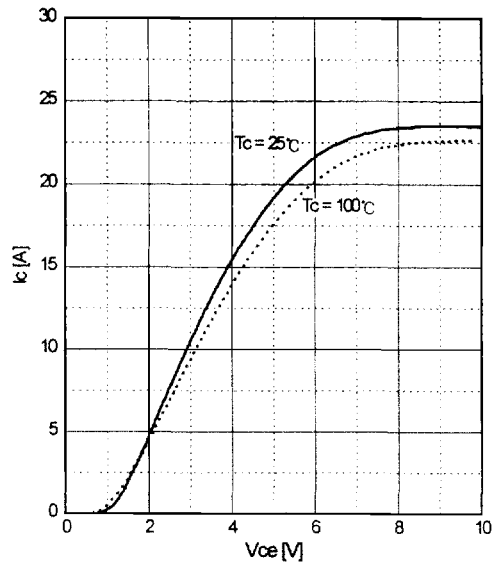


Fig.2 Typical Output Characteristics

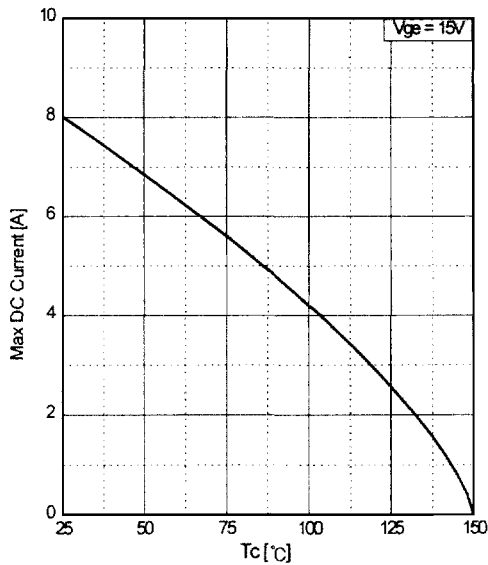


Fig.3 Maximum Collector Current vs. Case Temperature

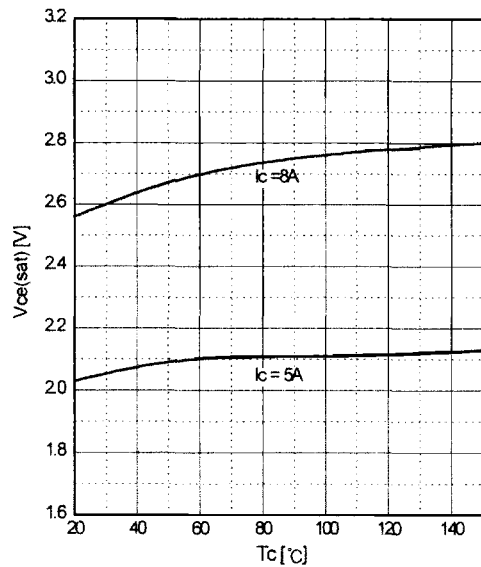
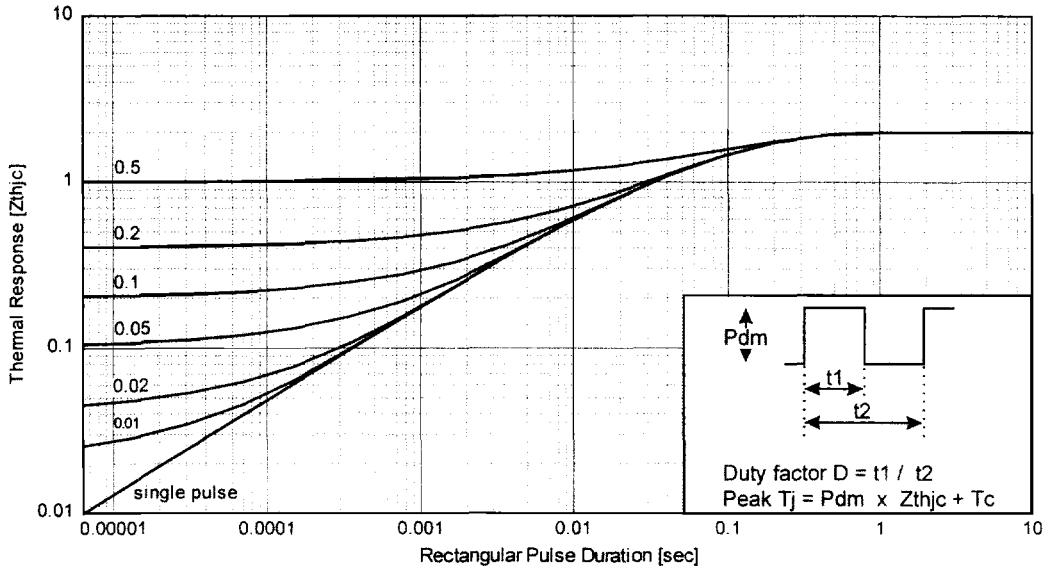


Fig.4 Collector to Emitter Voltage vs. Case Temperature



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Fig.5 Maximum Effective Transient Thermal Impedance, Junction to Case

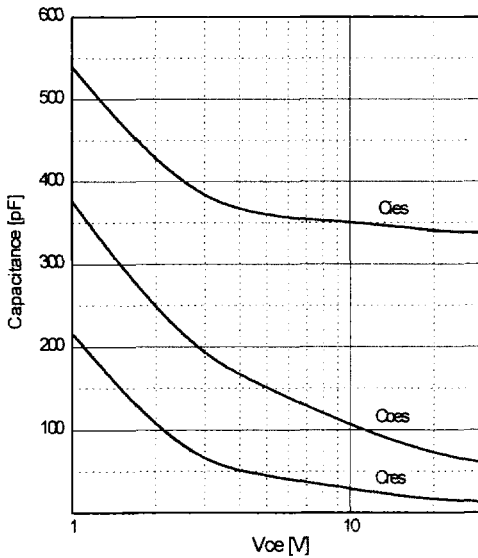


Fig.6 Typical Capacitance vs. Collector to Emitter Voltage

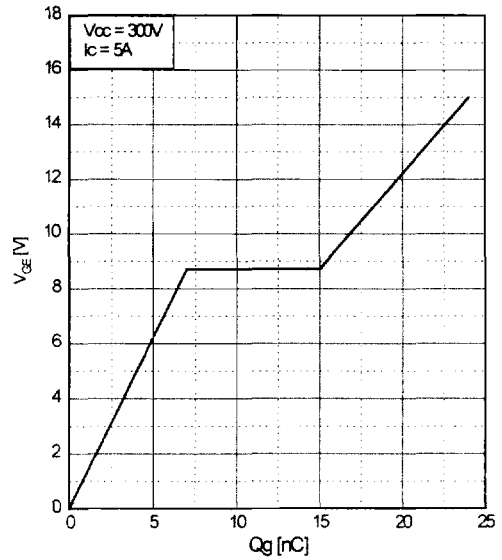


Fig.7 Typical Gate Charge vs. Gate to Emitter Voltage

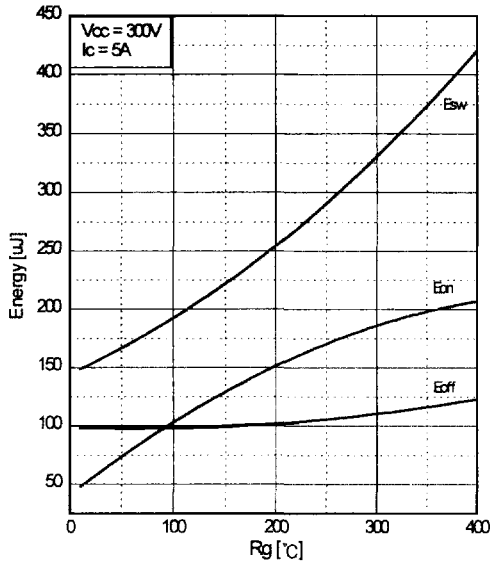


Fig.8 Typical Switching Loss vs. Gate Resistance

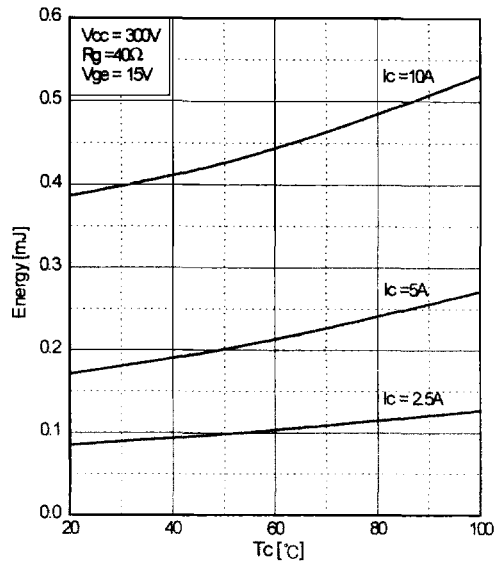


Fig.9 Typical Switching Loss vs. Case Temperature

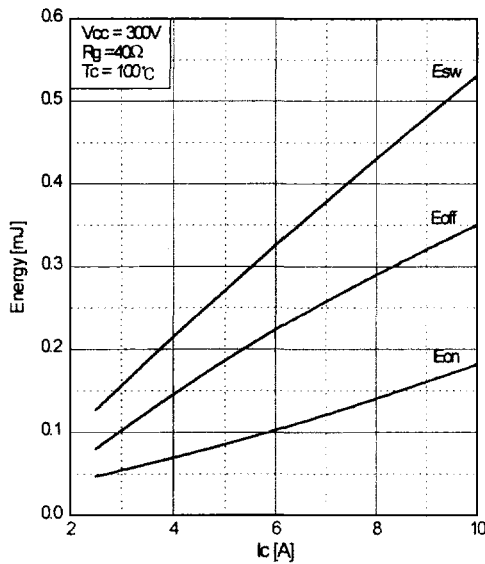


Fig.10 Typical Switching loss vs. Collector to Emitter Current

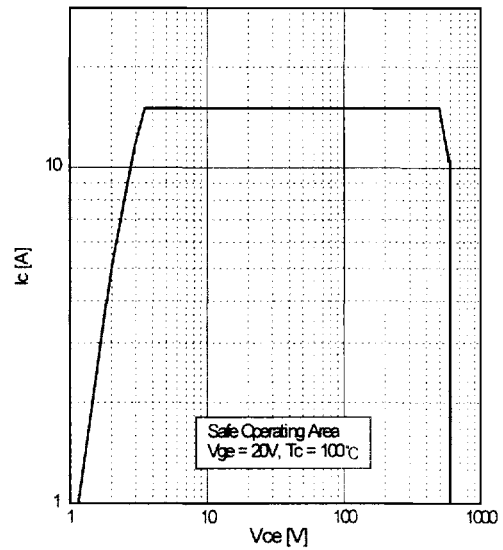


Fig.11 Turn-off SOA

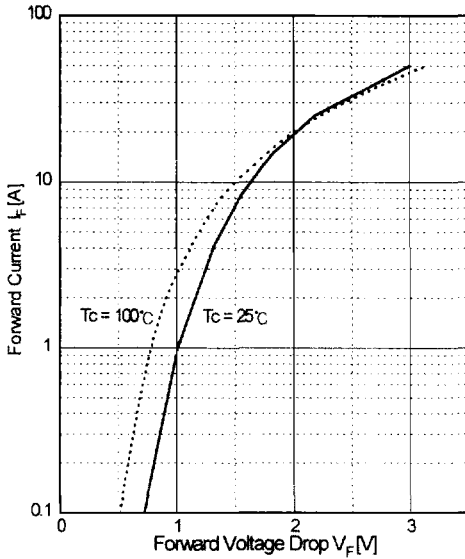


Fig.12 Typical Forward Voltage Drop vs. Forward Current

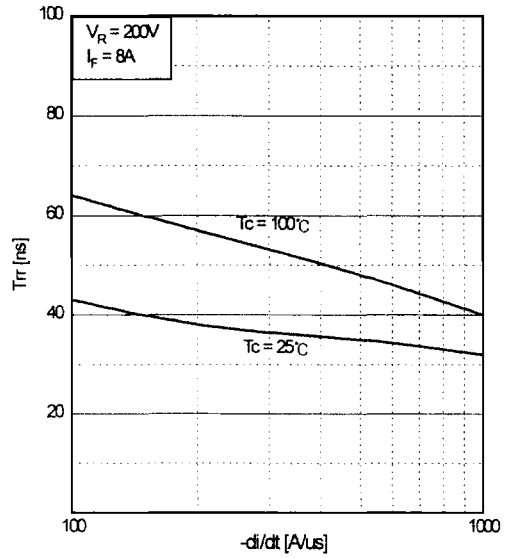


Fig.13 Typical Reverse Recovery Time vs. di/dt

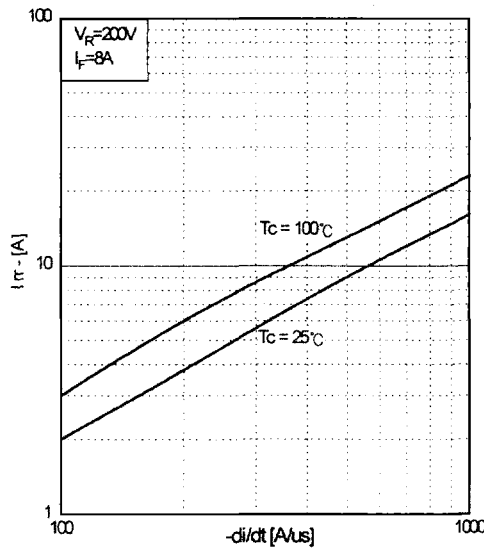


Fig.14 Typical Reverse Recovery Current vs. di/dt

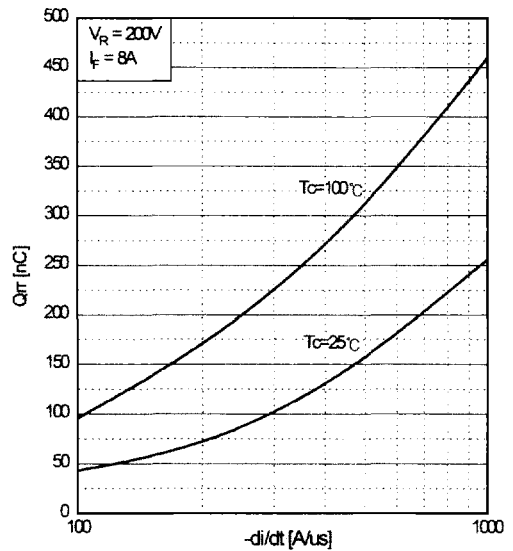


Fig.15 Typical Stored Charge vs. di/dt

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